

Application No. 10/761,685
Attorney Docket No.: 13631-48

REMARKS

This application has been reviewed in light of the Non-final Office Action dated January 24, 2006. Claim 35 is pending in this application. In view of the remarks presented below, Applicants respectfully request favorable reconsideration and allowance of Claim 35.

35 U.S.C. §102(B) REJECTION OF CLAIM 35 OVER U.S. PATENT NO. 5,381,944 ("MAKOWIECKI")

Claim 35 stands rejected under 35 U.S.C. §102(b) as anticipated by U.S. Patent No. 5,381,944 ("Makowiecki"). It is well-established that for a reference to defeat a claim's novelty under 35 U.S.C. § 102 (i.e., anticipate the claim), it must disclose each and every element of the claim. Advance Display Sys. v. Kent State Univ., 212 F.3d 1272 (Fed. Cir. 2000). Applicants respectfully request that this rejection be withdrawn because Makowiecki fails to teach each and every claim limitation called for in Claim 35.

In the present application, the claimed invention relates to a method of connecting a semiconductor or microelectronic device to a substrate. The method calls for the use of a reactive foil which reacts to form both conductive and non-conductive regions. Advantageously, the one or more conductive regions may then be registered with the electrical contacts of the device and the substrate to form an electrical connection, while the other portions of the device may be non-conductively bonded to the substrate using the one or more non-conductive regions. (Specification, page 22, lines 8-16).

Makowiecki is directed to a multi-layer foil including alternating layers of selected materials such as titanium (Ti) and boron (B) that react together to melt intermediary layers of fusible material, such as aluminum (Al), thus bonding the Ti and B layers together. (Makowiecki, column 2, line 52- column 3, line 3). However, Makowiecki fails to disclose a foil reacting to form both conductive and non-conductive regions. Furthermore, column 2, lines 50-

Application No. 10/761,685
Attorney Docket No.: 13631-48

65, the passage cited by the Examiner, does not provide a showing of a method for connecting a semiconductor or microelectronic device having one or more electrical contacts to a substrate having one or more receiving contacts. In addition, Makowiecki does not describe the registering of the contacts of the device, the contacts of the substrate, and the conductive regions of the foil.


In summary, Makowiecki does not disclose the use of foil that reacts to form both conductive and non-conductive regions and the registering of device contacts and substrate contacts to the conductive regions of the foil. Accordingly, because Makowiecki fails to disclose each and every element of the claimed invention, the § 102(b) rejection of Claim 35 should be withdrawn.

In view of the foregoing remarks, Applicants respectfully request favorable reconsideration and an early allowance of Claim 35.

No fee is believed due in connection with this Response. However, if a fee is deemed necessary in order to have this Response entered, please charge such fee to Deposit Account No. 501358.

Applicants' undersigned attorney may be reached by telephone at (973) 597-2500. All correspondence should continue to be directed to our address listed below.

Respectfully submitted,


Daniel D. Sierchio
Attorney for Applicants
Reg. No. 53,591

LOWENSTEIN, SANDLER PC
65 Livingston Avenue
Roseland, NJ 07068
Tel.: 973-597-2500
Fax.: 973-597-2400